

# Supporting Information

# Supporting Information S1.

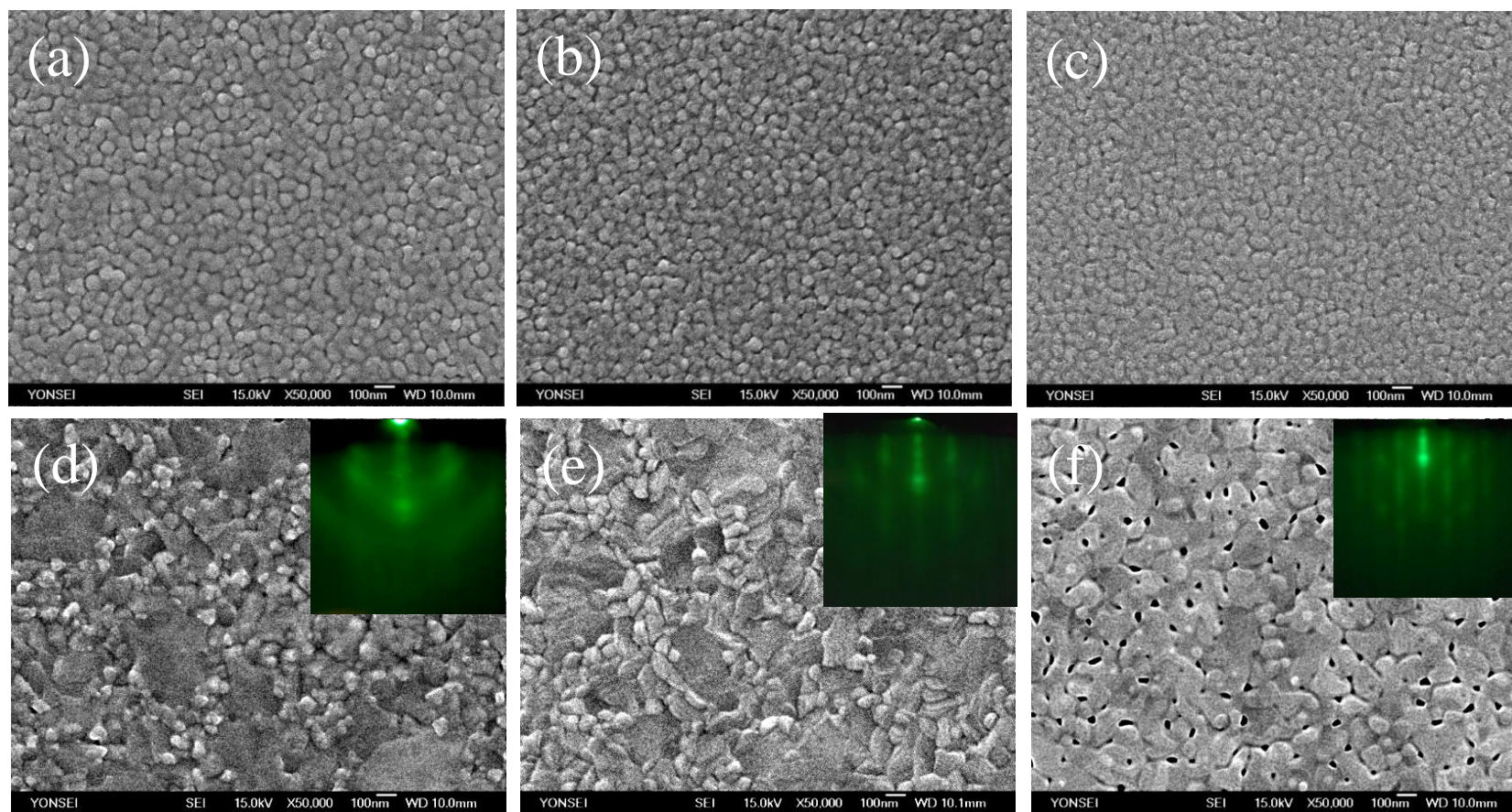


Figure S1. SEM images of the before annealing process (a)  $\{Sb(3)Te(3)\}_n$ , (b)  $\{Sb(4)Te(6)\}_n$ , (c)  $\{Sb(3)Te(9)\}_n$  and after annealing process (d)  $\{Sb(3)Te(3)\}_n$ , (e)  $\{Sb(3)Te(3)\}_n$ , (f)  $\{Sb(3)Te(3)\}_n$ . Inset images is *in-situ* RHEED pattern.

# Supporting Information S2.

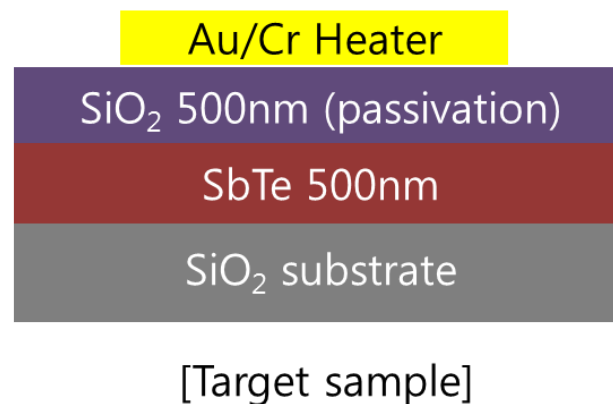
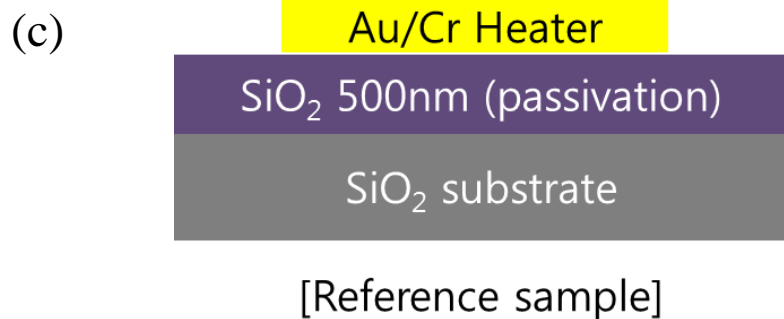
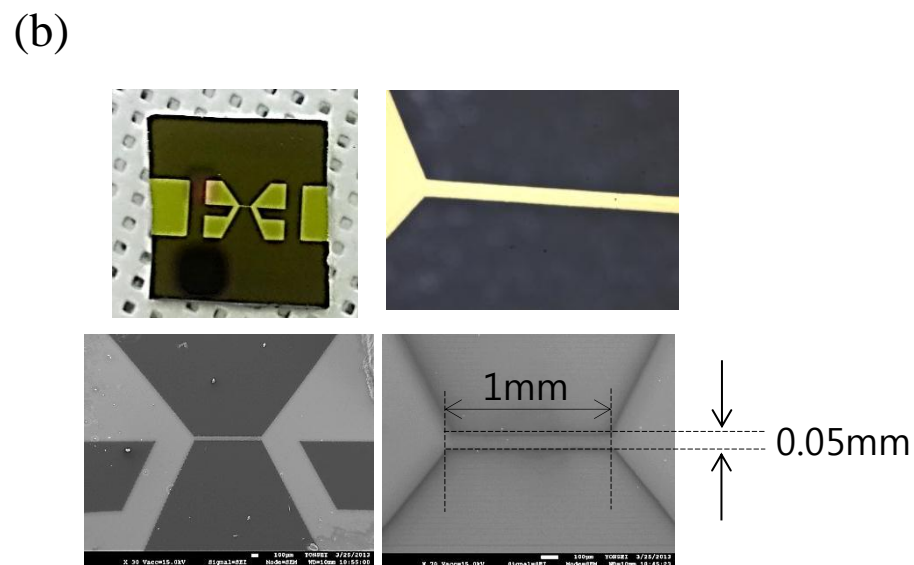
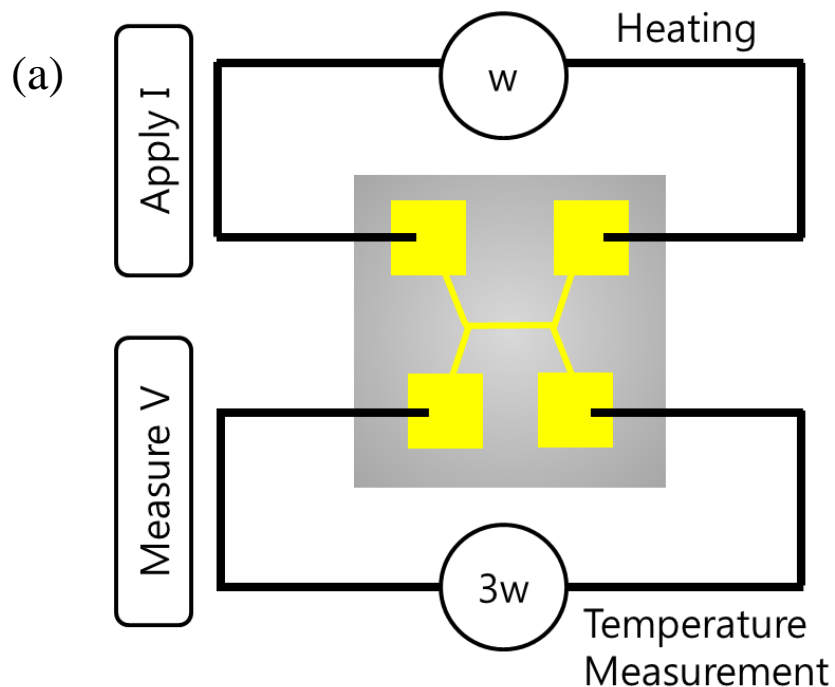


Figure S2. 3w method of thermal conductivity measurement (a) configuration of the 3w technique, (b) picture of 3w pattern sample and geometrical parameters of mask pattern (c) sample configuration for the differential 3w technique.

# Supporting Information S3.

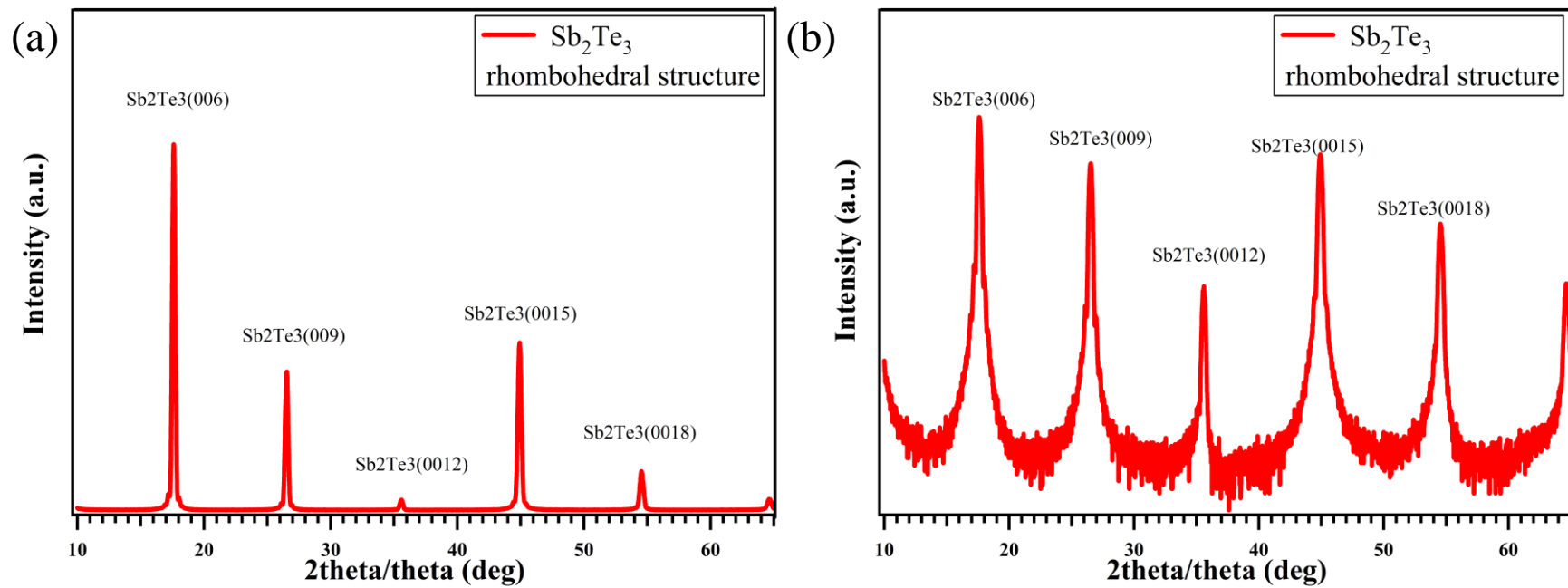


Figure S3. X-ray diffraction patterns of (a) the intensity (y-axis) scale for linear scale and (b) log scale for  $\{\text{Sb}(3)\text{Te}(9)\}_n$  after annealing process. Log scale XRD patterns shows that no Te crystal phase exists.

# Supporting Information S4.

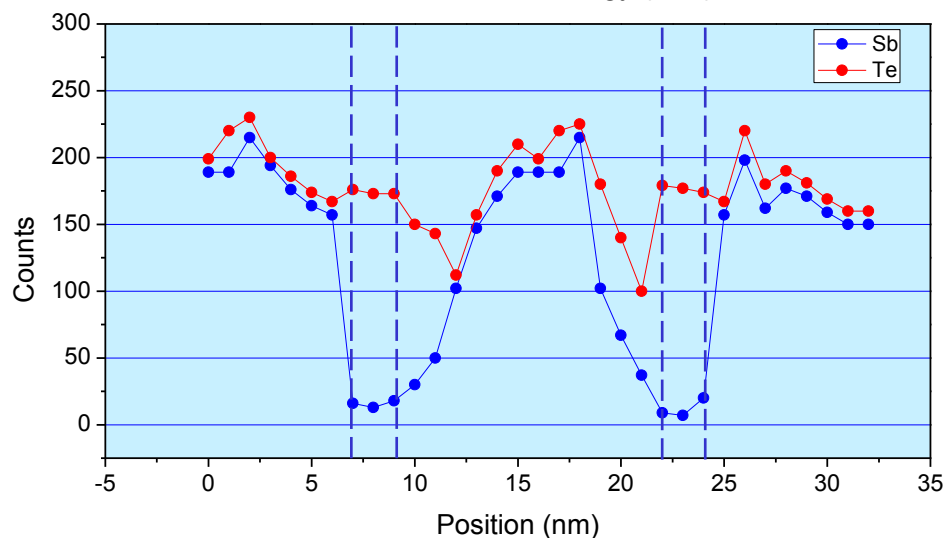
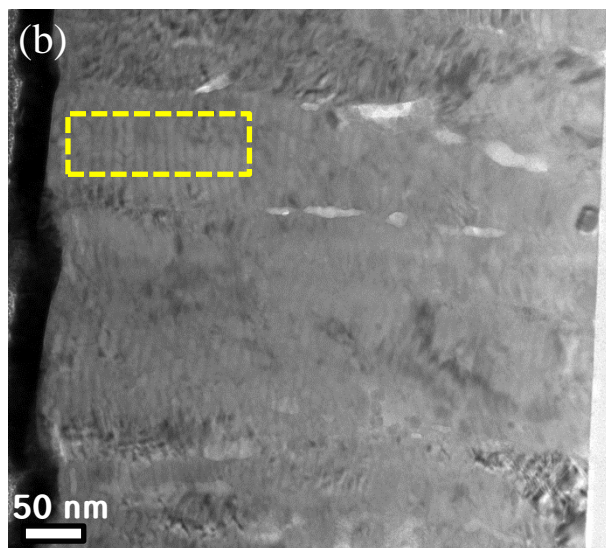
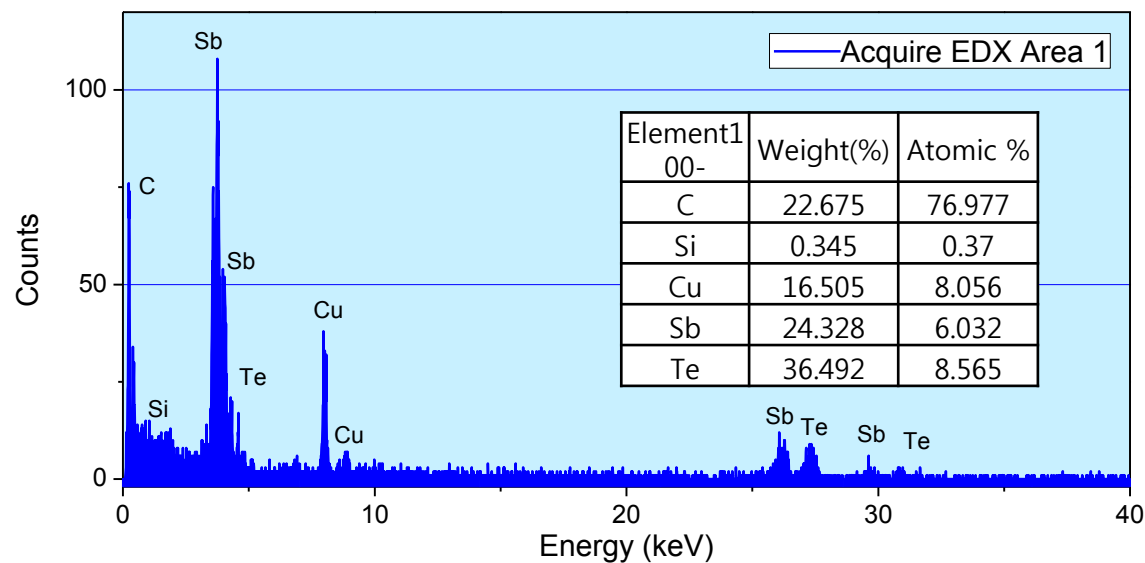
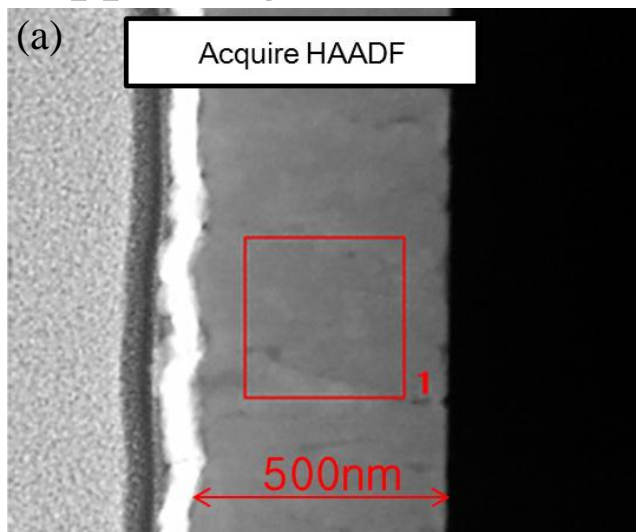


Figure S4. TEM image of  $\{\text{Sb}(4)\text{Te}(6)\}_n$  after annealing process (a) HAADF STEM image and EDX spectrum obtained from sample showing the stoichiometry of  $\{\text{Sb}(4)\text{Te}(6)\}_n$  sample, (b) STEM image and EDX line profile/mapping of Sb and Te elements.

# Supporting Information S5.

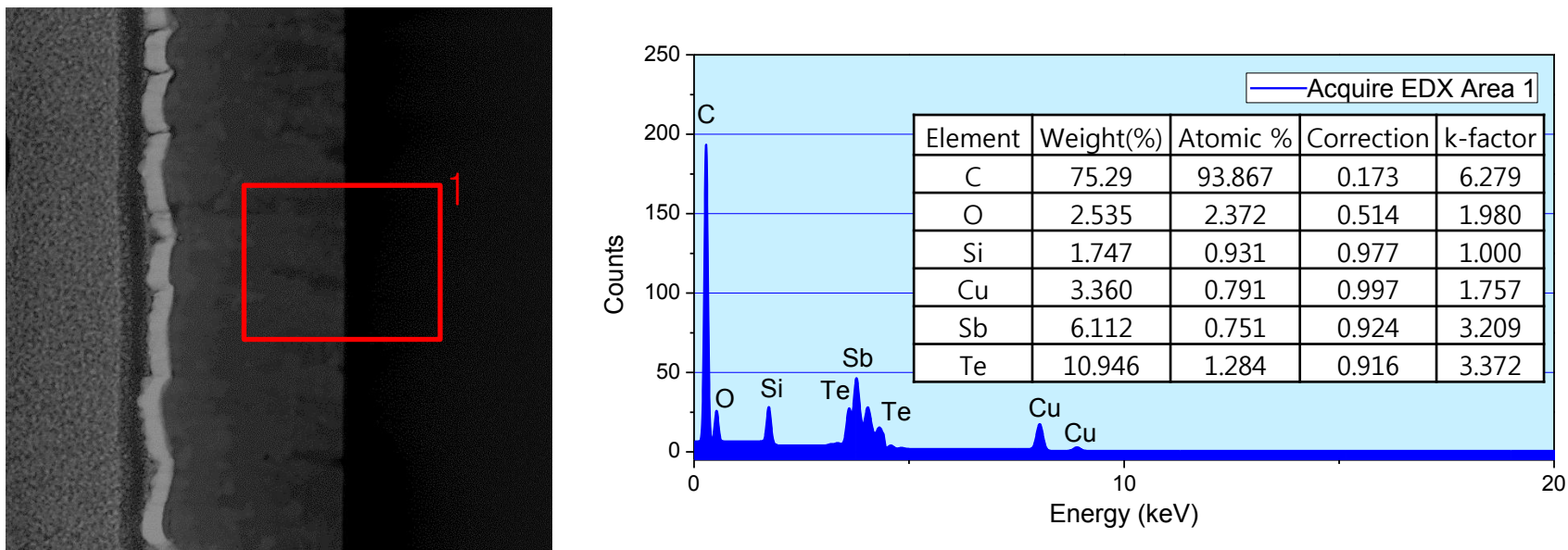


Figure S5. TEM image of  $\{\text{Sb}(4)\text{Te}(6)\}_n$  before annealing process (a) HAADF STEM image and (b) EDX spectrum obtained from sample showing the stoichiometry of  $\{\text{Sb}(4)\text{Te}(6)\}_n$  sample

# Supporting Information S6.

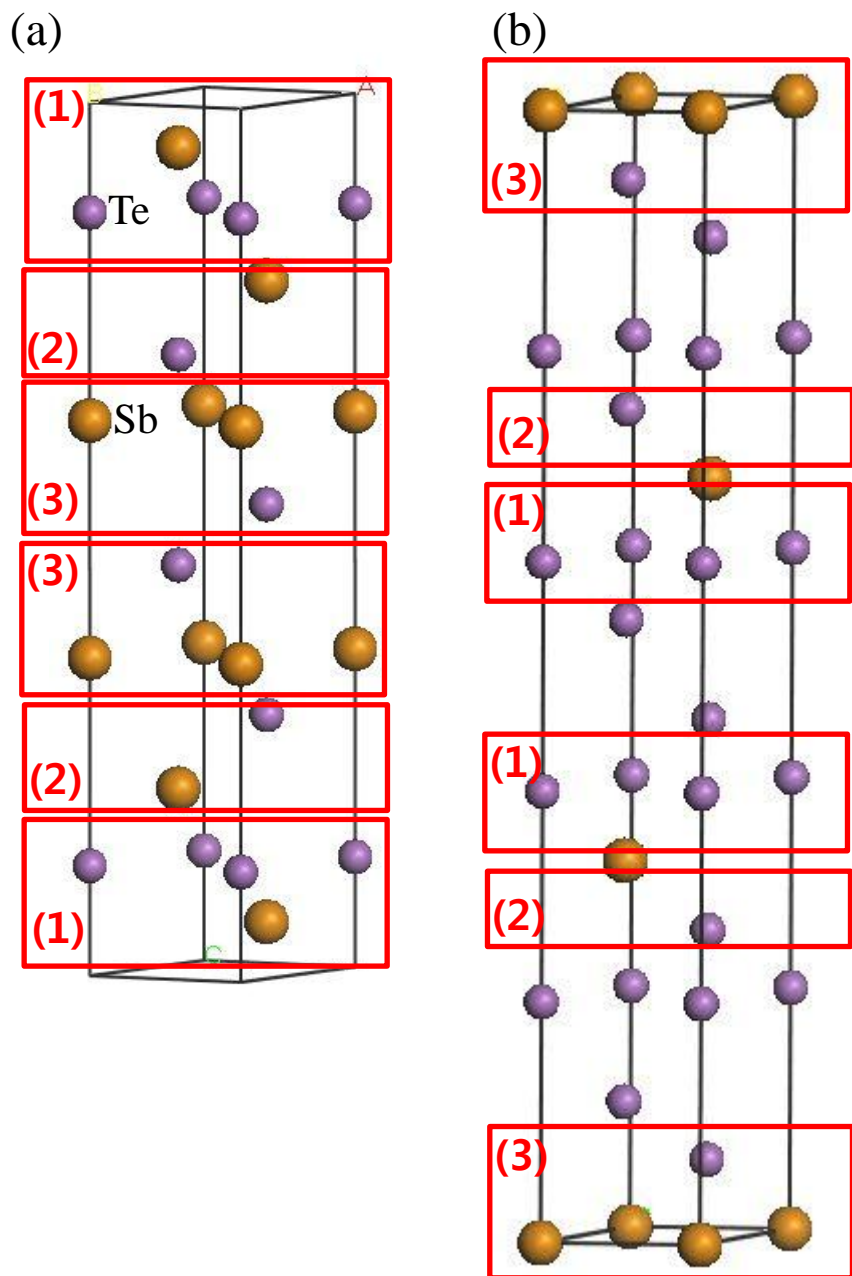


Figure S6. (a)  $\text{Sb}_2\text{Te}_2$  hexagonal unit cell and (b)  $\text{Sb}_2\text{Te}_3$  rhombohedral unit cell. Each of different Sb-Te Raman Vibration node denotes rectangular region with red color in (1),(2) and (3)

# Supporting Information S7.

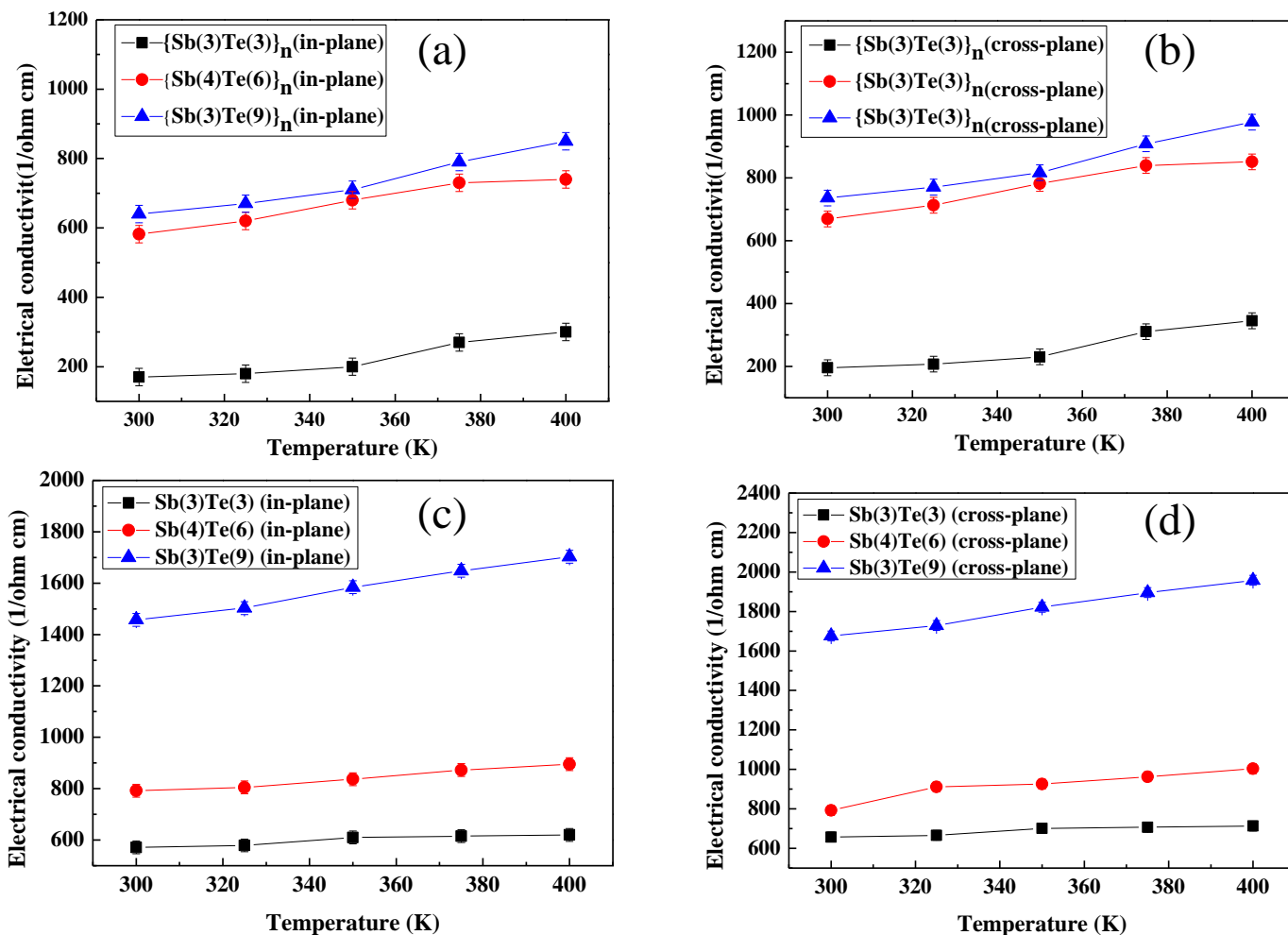


Figure S7 .Temperature dependence of electrical conductivity for (a) in-plane direction, (b) cross-plane direction of multilayered films after annealing, (c) in-plane direction and (d) cross-plane direction of co-deposited films after annealing.



# Supporting Information S8.

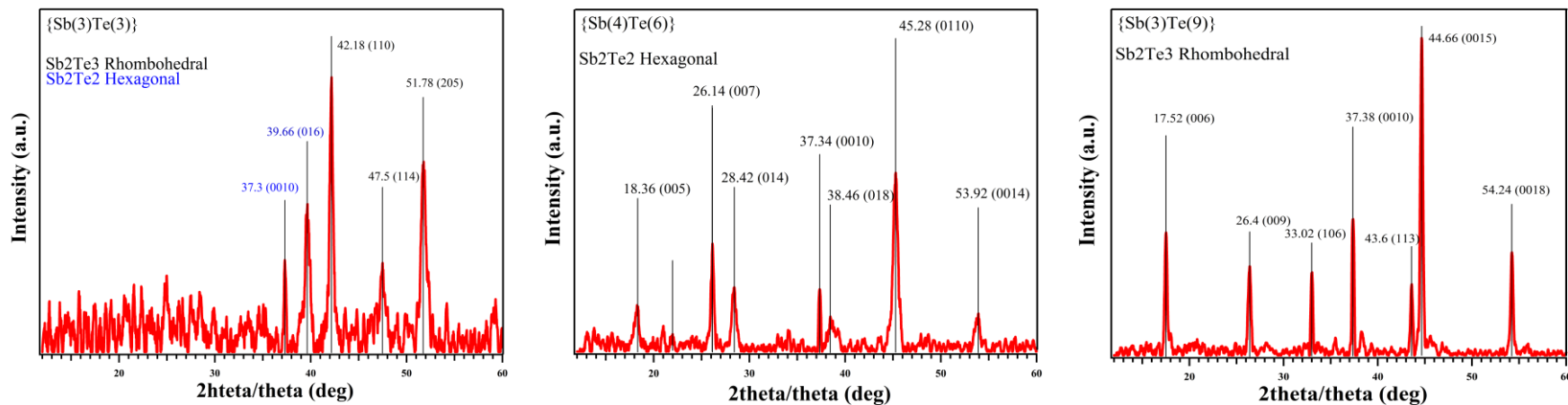


Figure S8. X-ray diffraction patterns of each co-deposited sample (a)Sb(3)Te(3), (b)Sb(4)Te(6) and (c) Sb(3)Te(9).

# Supporting Information Table S1.

		Layer	Density (g/cm <sup>3</sup> )	Thickness (nm)	Roughness (nm)	Repeat
{Sb(3)Te(3)} <sub>n</sub>	as-grown	Sb <sub>2</sub> Te <sub>2</sub>	6.57	470.98	3.3	1
		Sb <sub>2</sub> O <sub>3</sub>	4.86	0.09	2.0	1
	crystalline	Sb <sub>2</sub> Te <sub>2</sub>	5.99	480.39	4.3	1
		Sb <sub>2</sub> O <sub>3</sub>	6.33	1.52	7.7	1
		Layer	Density (g/cm <sup>3</sup> )	Thickness (nm)	Roughness (nm)	Repeat
{Sb(4)Te(6)} <sub>n</sub>	as-grown	Sb <sub>2</sub> Te <sub>2</sub>	5.90	450.10	2.2	1
		Sb <sub>2</sub> O <sub>3</sub>	5.41	0.8	3.63	1
	crystalline	Sb <sub>2</sub> Te <sub>2</sub>	6.65	10.32	4.32	40
		Te	5.15	0.88	4.43	
		Sb <sub>2</sub> O <sub>3</sub>	6.08	6.36	8.358	1
		Layer	Density (g/cm <sup>3</sup> )	Thickness (nm)	Roughness (nm)	Repeat
{Sb(3)Te(9)} <sub>n</sub>	as-grown	Sb <sub>2</sub> Te <sub>2</sub>	6.24	440.56	2.71	1
		Te	5.15	0.56	2.69	1
		Sb <sub>2</sub> O <sub>3</sub>	6.11	0.16	5.39	
	crystalline	Sb <sub>2</sub> Te <sub>2</sub>	6.26	470.68	5.38	1
		Sb <sub>2</sub> O <sub>3</sub>	6.88	0.22	4.82	1

Table S1. XRR fitting data for each sample in the before annealing process and after annealing process.

Post annealing (Crystalline) 300K	Carrier type	Carrier concentration (/cm <sup>3</sup> )	Carrier Mobility (cm <sup>2</sup> /Vs)	Electrical Resistivity (Ω cm)	Electrical Conductivity (1/Ω cm)	Seebeck Coefficient (μV/K)
{Sb(3)Te(3)} <sub>n</sub>	P	8.4 x 10 <sup>19</sup>	12.65	0.00588	170	110
{Sb(4)Te(6)} <sub>n</sub>	P	6.1 x 10 <sup>20</sup>	5.96	0.00171	582	102
{Sb(3)Te(9)} <sub>n</sub>	P	3.4 x 10 <sup>19</sup>	117.65	0.00156	640	127

Table S2. Hall measurement data and Seebeck coefficients for each sample obtained at room temperature.